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FORM	PTO-15	95
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U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: 070679-0263 103425	048 —————
To the Director of the U. S. Patent and 1.	documents of the new address(es) below.
1. Name of Conveying Party(ies)	2. Name and address of receiving party(ies)
Jae-Hyuk IM	Name: HYNIX SEMICONDUCTOR INC.
	Internal Address:
Additional name(s) of conveying party(ies) attached? Yes No	
3. Nature of Conveyance/Execution Date(s)	Address: San 136-1, Ami-ri, Bubal-eub, Ichon-shi,
	Kyoungki-do, 467-860, Republic of KOREA
Execution Date(s): June 27, 2007	
Security Agreement Change of Name	
Joint Research Agreement	
Government Interest Assignment	
Executive Order 9424, Confrmatory License	
Other	Additional name(s) & address(es) attached? Yes No
4. Application or patent number(s):	☐ This document is being filed together with a new application
A. Patent Application No(s).	B. Patent No(s).
•	
Additional numbers attac	
5. Name and address to whom correspondence concerning	6. Total number of applications and patents
document should be mailed:	involved: 7 Total fee (37 CFR 1 21(h) & 3.41) \$40.00
Name: MCDERMOTT WILL & EMERY LLP	7. Total lee (57 Cl R 1.21(11) as 51.11)
Internal Address:	Authorized to be charged by credit card
	Authorized to be charged to deposit account
Street Address: 600 13th Street, N.W.	Enclosed
	None required (government interest to affecting title)nt
City: Washington State: D. C. Zip: 20005-3096	
Phone Number: 202.756.8000	8. Payment Information:
Fax Number: 202.756.8087	o Credit Card Last 4 Numbers
Email Address:	a. Credit Card Last 4 Numbers
	Deposit Account Number 500417 \$ 9
,	Authorized User Name
9. Signature.	000 June 29, 2007
Stephen A. Becker, 26, 527	90ab
	Signature
Total number of pages include	ling cover sheet, attachments and documents:
OMB No. 0651-0027 (exp. 6/30/2008)	
OMB NO. 0031-0027 (0xp. 0.20	

PATENT REEL: 019546 FRAME: 0133

(SAB)		
Docket No.:		
ASS	GNMENT	
In consideration of the premises and othe ipt and sufficiency of which is hereby acknowled IM, Jae-Hyuk	r good and valuable consideration in hand paid, the rece ged, the undersigned,	
who has made a certain new and useful invention, Hynix Semiconductor Inc.	hereby sells, assigns and transfers unto	
its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled SEMICONDUCTOR MEMORY DEVICE		
	United States Letters Patent was filed on and identified by United States Serial No.	
; or		
(b) for which an application for Ut	nited States Letters Patent was executed on	
and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;		
AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.		
SIGNED on the date indicated aside my signature:		
INVENTOR	DATE SIGNED	
Janhyyk IM - Name: IM, Jac-Hyuk	June 27 , 2007	

PATENT REEL: 019546 FRAME: 0134

RECORDED: 06/29/2007